Wafer Sawing and Cleaning

Features

Fully Automatic Dicing Saw

- improved productivity with Φ300 mm wafers
- dual cut processing speed due to the shortened distance between the spindles.
- throughput improvement of approx. 7% compared to the previous model.
- Improves full cleaning capabilities (wheel cover effective against particle adhesion)
- Advanced graphical operation software
- Cutting speed, up to 1,000mm/s

CO2 Injector Resistivity Management Unit

- prevent particle adhesion and device damage caused by static electricity.

StayClean Injector (Water-soluble Additive)

- highest quality corrosion prevention* with particle countermeasures
- prevents bonding pad corrosion
- prevents hub blade corrosion and tapering
- prevents particle adhesion

SiC Wafer Sawing capability

- Ultrasonic wave dicing
- proven process technology with smaller grit size blade